Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm PCA</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries  Battery pack;RTC</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries N/A</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LED</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td>N/A</td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Phillips screwdriver (for 7 PCS on bottom case &amp; 8 PCS on Ucase &amp; 6 PCS Base side hinge bracket)</td>
<td>T8 2.55~3.45 kg-cm</td>
</tr>
<tr>
<td>Description #2 Phillips screwdriver (for 1 PCS on sever door and 2 PCS on Keyboard)</td>
<td>#1 2.55~3.45 kg-cm</td>
</tr>
<tr>
<td>Description #3 Phillips screwdriver (for 7 PCS on PCB &amp; 4 PCS on BATTERY &amp; 1 PCS on SPK &amp; 8 PCS on LCD side hinge bracket)</td>
<td>#1 2.55~3.45 kg-cm</td>
</tr>
<tr>
<td>Description #4 Use jig disassemble Lcd Bezel with Lcd cover</td>
<td>Pick thickness 0.3~0.4mm</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Release 1 PCS Phillips screw from Service Door refer figure 1
2. Release 7pcs T8 screw and 2 PCS Phillips from bottom case refer figure 2
3. Disassembly: WLAN cable refer figure 3
4. Use tool to push Keyboard from arrow location refer figure 4
5. Disassembly: KB FPC, Click pad FFC, FPR FFC refer figure 5
6. Release 8 Pcs Phillips screw from U case refer figure 6
7. Two hand together disassemble Top case from arrow side refer figure 7
8. Release 4 Pcs Phillips screw from Battery, Next remove it refer figure 8
9. Disassembly: DC-in cable, CCD cable, EDP cable, Touch cable, SPK cable, daughter board FPC, Power FFC refer figure 9
10. Release 8 Pcs Phillips screw from PCB and SPK, Next teardown mainboard and daughter board refer figure 10
11. Release 6pcs T8 screw from base side hinge bracket refer figure 11
12. Disassemble LCD module initial step pick insert gap between LCD Cover and LCD Bezel refer figure 12
13. Release 8pcs Phillips screw from right & left hinge Bracket refer figure 13
14.
15.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Release 1pcs Phillips from service door

   Use Phillips screwdriver

   Figure 1

1. Disassemble WLAN cable

   Figure 3

1. Release 7pcs T8 screw from base case
2. Release 2pcs Phillips screw from base case

   Use T8 screwdriver & Phillips screwdriver

   Figure 2

1. Disassemble keyboard location

   Figure 4
1. Disassembly: KB FPC  
   Click pad FFC  
   FPR FFC

Figure 5

1. Release 8 Pcs T8 screw from U case

Use T8 screwdriver

Figure 6

1. Two hand together dissemble Top case from arrow side

Figure 7

1. Release 4 Pcs Phillips screw from battery

Use Phillips screwdriver

Figure 8
1. Disassembly: DC-in cable, CCD cable, EDP cable, Touch cable, SPK cable, daughter board FPC, Power FFC

Figure 9

1. Release 8 pcs Phillips screw from PCB and SPK.

Use Phillips screwdriver

Figure 10

1. Release 6 pcs T8 screw from base side hinge bracket

Use T8 screwdriver

Figure 11

1. Disassemble LCD module initial step pick insert gap between LCD Cover and LCD Bezel

Pick thickness 0.3~0.4mm

Figure 12

1. Release 8 pcs Phillips screw from right & left hinge Bracket

Use Phillips screwdriver

Figure 13